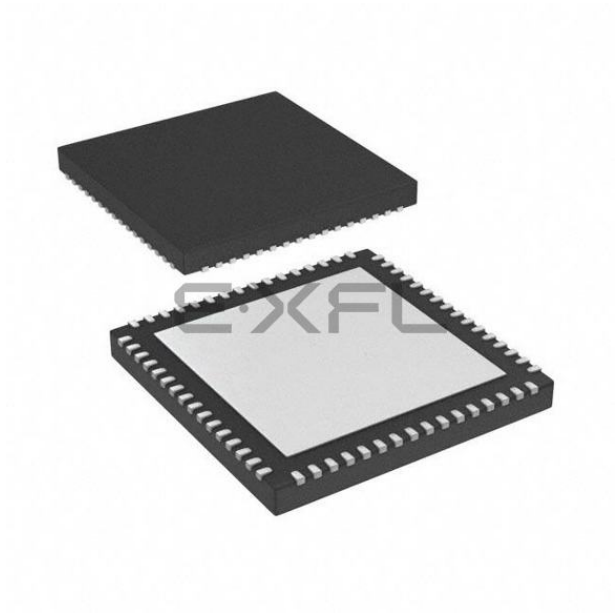


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx130f128h-i-mr

TABLE 1: PIC32MX1XX/2XX/5XX 64/100-PIN CONTROLLER FAMILY FEATURES

Device	Pins	Packages(4)	Program Memory (KB)(1)	Data Memory (KB)	Remappable Peripherals					10-bit 1 Msps ADC (Channels)	Analog Comparators	USB On-The-Go (OTG)	CAN	CTMU	I^2C	PMP	RTCC	DMA Channels (Programmable/Dedicated)	I/O Pins	JTAG
					Remappable Pins	Timers/Capture/Compare(2)	UART	SPI/I^2S	External Interrupts(3)											
PIC32MX120F064H	64	QFN, TQFP	64+3	8	37	5/5/5	4	3	5	28	3	N	0	Y	2	Y	Y	4/0	53	Y
PIC32MX130F128H	64	QFN, TQFP	128+3	16	37	5/5/5	4	3	5	28	3	N	0	Y	2	Y	Y	4/0	53	Y
PIC32MX130F128L	100	TQFP	128+3	16	54	5/5/5	5	4	5	48	3	N	0	Y	2	Y	Y	4/0	85	Y
	100	TFBGA																		
PIC32MX230F128H	64	QFN, TQFP	128+3	16	37	5/5/5	4	3	5	28	3	Y	0	Y	2	Y	Y	4/2	49	Y
PIC32MX230F128L	100	TQFP	128+3	16	54	5/5/5	5	4	5	48	3	Y	0	Y	2	Y	Y	4/2	81	Y
	100	TFBGA																		
PIC32MX530F128H	64	QFN, TQFP	128+3	16	37	5/5/5	4	3	5	28	3	Y	1	Y	2	Y	Y	4/4	49	Y
PIC32MX530F128L	100	TQFP	128+3	16	54	5/5/5	5	4	5	48	3	Y	1	Y	2	Y	Y	4/4	81	Y
	100	TFBGA																		
PIC32MX150F256H	64	QFN, TQFP	256+3	32	37	5/5/5	4	3	5	28	3	N	0	Y	2	Y	Y	4/0	53	Y
PIC32MX150F256L	100	TQFP	256+3	32	54	5/5/5	5	4	5	48	3	N	0	Y	2	Y	Y	4/0	85	Y
	100	TFBGA																		
PIC32MX250F256H	64	QFN, TQFP	256+3	32	37	5/5/5	4	3	5	28	3	Y	0	Y	2	Y	Y	4/2	49	Y
PIC32MX250F256L	100	TQFP	256+3	32	54	5/5/5	5	4	5	48	3	Y	0	Y	2	Y	Y	4/2	81	Y
	100	TFBGA																		
PIC32MX550F256H	64	QFN, TQFP	256+3	32	37	5/5/5	4	3	5	28	3	Y	1	Y	2	Y	Y	4/4	49	Y
PIC32MX550F256L	100	TQFP	256+3	32	54	5/5/5	5	4	5	48	3	Y	1	Y	2	Y	Y	4/4	81	Y
	100	TFBGA																		
PIC32MX170F512H	64	QFN, TQFP	512+3	64	37	5/5/5	4	3	5	28	3	N	0	Y	2	Y	Y	4/0	53	Y
PIC32MX170F512L	100	TQFP	512+3	64	54	5/5/5	5	4	5	48	3	N	0	Y	2	Y	Y	4/0	85	Y
	100	TFBGA																		
PIC32MX270F512H	64	QFN, TQFP	512+3	64	37	5/5/5	4	3	5	28	3	Y	0	Y	2	Y	Y	4/2	49	Y
PIC32MX270F512L	100	TQFP	512+3	64	54	5/5/5	5	4	5	48	3	Y	0	Y	2	Y	Y	4/2	81	Y
	100	TFBGA																		
PIC32MX570F512H	64	QFN, TQFP	512+3	64	37	5/5/5	4	3	5	28	3	Y	1	Y	2	Y	Y	4/4	49	Y
PIC32MX570F512L	100	TQFP	512+3	64	54	5/5/5	5	4	5	48	3	Y	1	Y	2	Y	Y	4/4	81	Y
	100	TFBGA																		

Note 1: All devices feature 3 KB of Boot Flash memory.
2: Four out of five timers are remappable.
3: Four out of five external interrupts are remappable.
4: Please contact your local Microchip Sales Office for information regarding the availability of devices in the 100-pin TFBGA package.

TABLE 5: PIN NAMES FOR 100-PIN USB DEVICES (CONTINUED)

100-PIN TQFP (TOP VIEW)

PIC32MX230F128L
PIC32MX530F128L
PIC32MX250F256L
PIC32MX550F256L
PIC32MX270F512L
PIC32MX570F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
71	RPD11/PMA14/RD11	86	VDD
72	RPD0/INT0/RD0	87	AN44/C3INA/RPF0/PMD11/RF0
73	SOSCI/RPC13/RC13	88	AN45/RPF1/PMD10/RF1
74	SOSCO/RPC14/T1CK/RC14	89	RPG1/PMD9/RG1
75	VSS	90	RPG0/PMD8/RG0
76	AN24/RPD1/RD1	91	RA6
77	AN25/RPD2/RD2	92	CTED8/RA7
78	AN26/C3IND/RPD3/RD3	93	AN46/PMD0/RE0
79	AN40/RPD12/PMD12/RD12	94	AN47/PMD1/RE1
80	AN41/PMD13/RD13	95	RG14
81	RPD4/PMWR/RD4	96	RG12
82	RPD5/PMRD/RD5	97	RG13
83	AN42/C3INC/PMD14/RD6	98	AN20/PMD2/RE2
84	AN43/C3INB/PMD15/RD7	99	RPE3/CTPLS/PMD3/RE3
85	VCAP	100	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP			
RTCC	42	68	O	—	Real-Time Clock Alarm Output
CVREFOUT	23	34	O	Analog	Comparator Voltage Reference (Output)
C1INA	11	20	I	Analog	Comparator 1 Inputs
C1INB	12	21	I	Analog	
C1INC	5	11	I	Analog	
C1IND	4	10	I	Analog	
C2INA	13	22	I	Analog	Comparator 2 Inputs
C2INB	14	23	I	Analog	
C2INC	8	14	I	Analog	
C2IND	6	12	I	Analog	
C3INA	58	87	I	Analog	Comparator 3 Inputs
C3INB	55	84	I	Analog	
C3INC	54	83	I	Analog	
C3IND	51	78	I	Analog	
C1OUT	PPS	PPS	O	—	Comparator 1 Output
C2OUT	PPS	PPS	O	—	Comparator 2 Output
C3OUT	PPS	PPS	O	—	Comparator 3 Output
PMALL	30	44	O	TTL/ST	Parallel Master Port Address Latch Enable Low Byte
PMALH	29	43	O	TTL/ST	Parallel Master Port Address Latch Enable High Byte
PMA0	30	44	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)
PMA1	29	43	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)

Legend: CMOS = CMOS compatible input or output Analog = Analog input I = Input O = Output
ST = Schmitt Trigger input with CMOS levels TTL = TTL input buffer P = Power

Note 1: This pin is only available on devices without a USB module.

2: This pin is only available on devices with a USB module.

3: This pin is not available on 64-pin devices with a USB module.

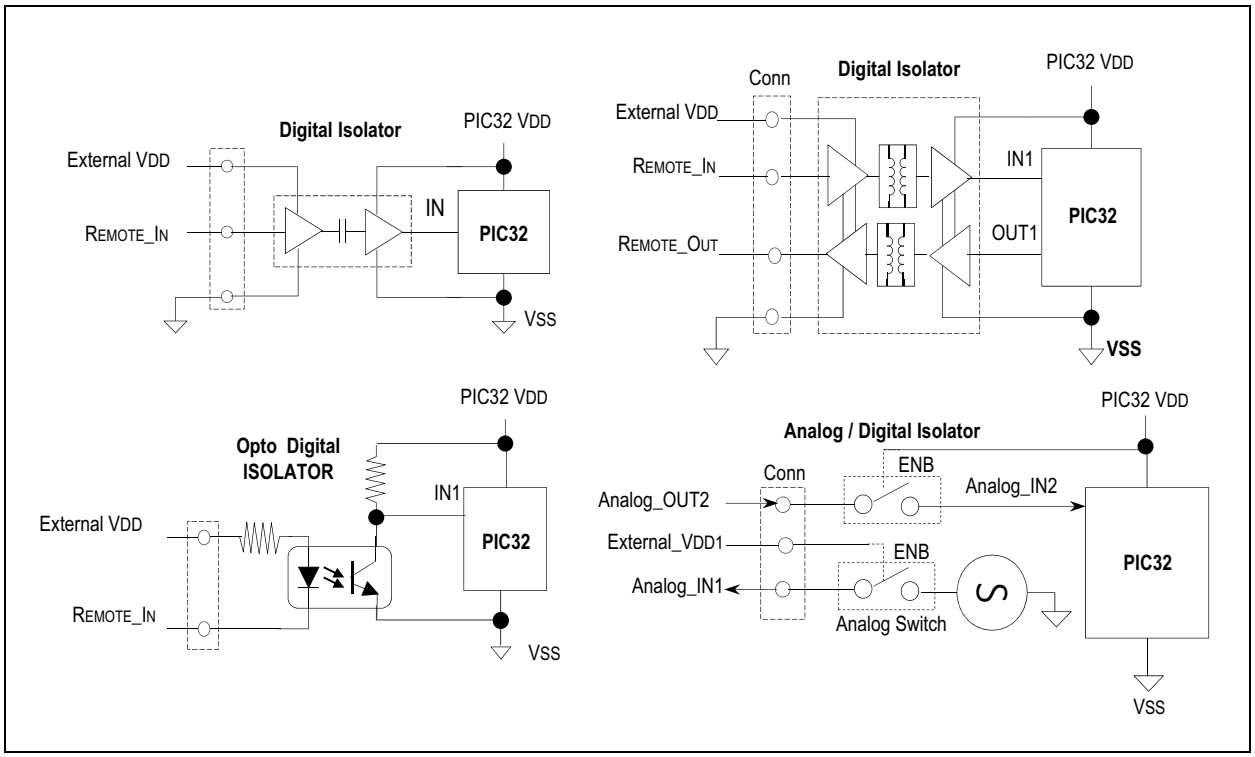
4: This pin is only available on 100-pin devices without a USB module.

Without proper signal isolation, on non-5V tolerant pins, the remote signal can power the PIC32 device through the high side ESD protection diodes. Besides violating the absolute maximum rating specification when VDD of the PIC32 device is restored and ramping up or ramping down, it can also negatively affect the internal Power-on Reset (POR) and Brown-out Reset (BOR) circuits, which can lead to improper initialization of internal PIC32 logic circuits. In these cases, it is recommended to implement digital or analog signal isolation as depicted in Figure 2-6, as appropriate. This is indicative of all industry microcontrollers and not just Microchip products.

TABLE 2-1: EXAMPLES OF DIGITAL/ ANALOG ISOLATORS WITH OPTIONAL LEVEL TRANSLATION

Example Digital/Analog Signal Isolation Circuits	Inductive Coupling	Capacitive Coupling	Opto Coupling	Analog/Digital Switch
ADuM7241 / 40 ARZ (1 Mbps)	X	—	—	—
ADuM7241 / 40 CRZ (25 Mbps)	X	—	—	—
ISO721	—	X	—	—
LTV-829S (2 Channel)	—	—	X	—
LTV-849S (4 Channel)	—	—	X	—
FSA266 / NC7WB66	—	—	—	X

FIGURE 2-6: DIGITAL/ANALOG SIGNAL ISOLATION CIRCUITS



REGISTER 4-2: BMXDKPBA: DATA RAM KERNEL PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDKPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDKPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDKPBA<15:10>:** DRM Kernel Program Base Address bits
When non-zero, this value selects the relative base address for kernel program space in RAM

bit 9-0 **BMXDKPBA<9:0>:** Read-Only bits
Value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernel mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

NOTES:

REGISTER 5-1: INTCON: INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
	—	—	—	MVEC	—	TPC<2:0>		
7:0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-13 **Unimplemented:** Read as '0'

bit 12 **MVEC:** Multi Vector Configuration bit
- 1 = Interrupt controller configured for multi vectored mode
- 0 = Interrupt controller configured for single vectored mode

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **TPC<2:0>:** Interrupt Proximity Timer Control bits
- 111 = Interrupts of group priority 7 or lower start the Interrupt Proximity timer
- 110 = Interrupts of group priority 6 or lower start the Interrupt Proximity timer
- 101 = Interrupts of group priority 5 or lower start the Interrupt Proximity timer
- 100 = Interrupts of group priority 4 or lower start the Interrupt Proximity timer
- 011 = Interrupts of group priority 3 or lower start the Interrupt Proximity timer
- 010 = Interrupts of group priority 2 or lower start the Interrupt Proximity timer
- 001 = Interrupts of group priority 1 start the Interrupt Proximity timer
- 000 = Disables Interrupt Proximity timer

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **INT4EP:** External Interrupt 4 Edge Polarity Control bit
- 1 = Rising edge
- 0 = Falling edge

bit 3 **INT3EP:** External Interrupt 3 Edge Polarity Control bit
- 1 = Rising edge
- 0 = Falling edge

bit 2 **INT2EP:** External Interrupt 2 Edge Polarity Control bit
- 1 = Rising edge
- 0 = Falling edge

bit 1 **INT1EP:** External Interrupt 1 Edge Polarity Control bit
- 1 = Rising edge
- 0 = Falling edge

bit 0 **INT0EP:** External Interrupt 0 Edge Polarity Control bit
- 1 = Rising edge
- 0 = Falling edge

REGISTER 8-3: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 3-0 **ROSEL<3:0>:** Reference Clock Source Select bits(1)

1111 = Reserved; do not use
•
•
•
1001 = Reserved; do not use
1000 = REFCLKI
0111 = System PLL output
0110 = USB PLL output
0101 = SOSC
0100 = LPRC
0011 = FRC
0010 = POSC
0001 = PBCLK
0000 = SYSCLK

Note 1: The ROSEL and RODIV bits should not be written while the ACTIVE bit is '1', as undefined behavior may result.

2: This bit is ignored when the ROSEL<3:0> bits = 0000 or 0001.

3: While the ON bit is set to '1', writes to these bits do not take effect until the DIVSWEN bit is also set to '1'.

REGISTER 10-18: U1BDTP2: USB BDT PAGE 2 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRH<23:16>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRH<23:16>:** BDT Base Address bits

This 8-bit value provides address bits 23 through 16 of the BDT base address, which defines the starting location of the BDT in system memory.

The 32-bit BDT base address is 512-byte aligned.

REGISTER 10-19: U1BDTP3: USB BDT PAGE 3 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRU<31:24>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRU<31:24>:** BDT Base Address bits

This 8-bit value provides address bits 31 through 24 of the BDT base address, defines the starting location of the BDT in system memory.

The 32-bit BDT base address is 512-byte aligned.

REGISTER 12-1: T1CON: TYPE A TIMER CONTROL REGISTER (CONTINUED)

bit 2 **TSYNC:** Timer External Clock Input Synchronization Selection bit

When TCS = 1:

1 = External clock input is synchronized

0 = External clock input is not synchronized

When TCS = 0:

This bit is ignored.

bit 1 **TCS:** Timer Clock Source Select bit

1 = External clock from TxCKI pin

0 = Internal peripheral clock

bit 0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

14.0 WATCHDOG TIMER (WDT)

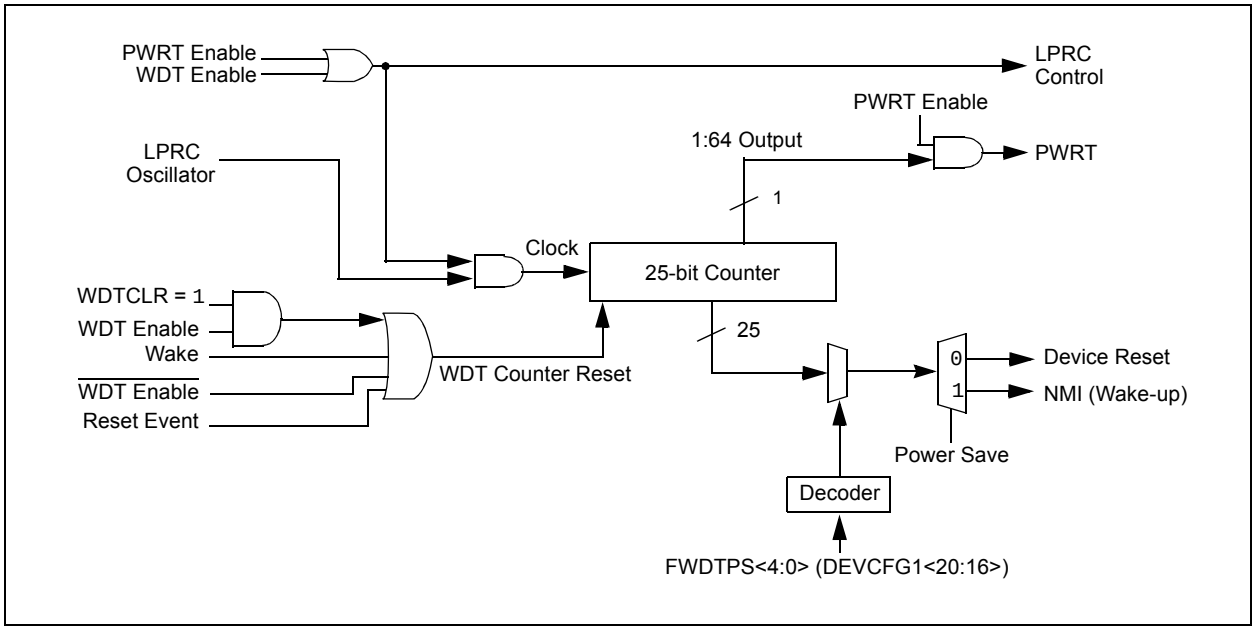
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin Family family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog, Deadman, and Power-up Timers"** (DS60001114) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

The Watchdog Timer (WDT), when enabled, operates from the internal Low-Power Oscillator (LPRC) clock source and can be used to detect system software malfunctions by resetting the device if the WDT is not cleared periodically in software. Various WDT time-out periods can be selected using the WDT postscaler. The WDT can also be used to wake the device from Sleep or Idle mode.

The following are some of the key features of the WDT module:

- Configuration or software controlled
- User-configurable time-out period
- Can wake the device from Sleep or Idle

FIGURE 14-1: WATCHDOG AND POWER-UP TIMER BLOCK DIAGRAM



REGISTER 23-14: C1RXFn: CAN ACCEPTANCE FILTER 'n' REGISTER ('n' = 0 THROUGH 15)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	SID<10:3>							
23:16	R/W-x	R/W-x	R/W-x	U-0	R/W-0	U-0	R/W-x	R/W-x
	SID<2:0>			—	EXID	—	EID<17:16>	
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	EID<15:8>							
7:0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	EID<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-21 **SID<10:0>:** Standard Identifier bits
1 = Message address bit SIDx must be '1' to match filter
0 = Message address bit SIDx must be '0' to match filter

bit 20 **Unimplemented:** Read as '0'

bit 19 **EXID:** Extended Identifier Enable bits
1 = Match only messages with extended identifier addresses
0 = Match only messages with standard identifier addresses

bit 18 **Unimplemented:** Read as '0'

bit 17-0 **EID<17:0>:** Extended Identifier bits
1 = Message address bit EIDx must be '1' to match filter
0 = Message address bit EIDx must be '0' to match filter

Note: This register can only be modified when the filter is disabled (FLTENn = 0).

REGISTER 23-18: C1FIFOUAn: CAN FIFO USER ADDRESS REGISTER 'n' ('n' = 0 THROUGH 15)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R-x	R-x	R-x	R-x	R-x	R-x	R-x	R-x
	C1FIFOUAn<31:24>							
23:16	R-x	R-x	R-x	R-x	R-x	R-x	R-x	R-x
	C1FIFOUAn<23:16>							
15:8	R-x	R-x	R-x	R-x	R-x	R-x	R-x	R-x
	C1FIFOUAn<15:8>							
7:0	R-x	R-x	R-x	R-x	R-x	R-x	R-0(1)	R-0(1)
	C1FIFOUAn<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **C1FIFOUAn<31:0>:** CAN FIFO User Address bits

TXEN = 1: (FIFO configured as a transmit buffer)

A read of this register will return the address where the next message is to be written (FIFO head).

TXEN = 0: (FIFO configured as a receive buffer)

A read of this register will return the address where the next message is to be read (FIFO tail).

Note 1: This bit will always read '0', which forces byte-alignment of messages.

Note: This register is not guaranteed to read correctly in Configuration mode, and should only be accessed when the module is not in Configuration mode.

REGISTER 23-19: C1FIFOCIn: CAN MODULE MESSAGE INDEX REGISTER 'n' ('n' = 0 THROUGH 15)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
	—	—	—	C1FIFOCIn<4:0>				

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-5 **Unimplemented:** Read as '0'

bit 4-0 **C1FIFOCIn<4:0>:** CAN Side FIFO Message Index bits

TXEN = 1: (FIFO configured as a transmit buffer)

A read of this register will return an index to the message that the FIFO will next attempt to transmit.

TXEN = 0: (FIFO configured as a receive buffer)

A read of this register will return an index to the message that the FIFO will use to save the next message.

27.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. "Power-Saving Features"** (DS60001130) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

This section describes power-saving features for the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. These PIC32 devices offer a total of nine methods and modes, organized into two categories, that allow the user to balance power consumption with device performance. In all of the methods and modes described in this section, power-saving is controlled by software.

27.1 Power Saving with CPU Running

When the CPU is running, power consumption can be controlled by reducing the CPU clock frequency, lowering the PBCLK and by individually disabling modules. These methods are grouped into the following categories:

- FRC Run mode: the CPU is clocked from the FRC clock source with or without postscalers.
- LPRC Run mode: the CPU is clocked from the LPRC clock source.
- SOSC Run mode: the CPU is clocked from the SOSC clock source.

In addition, the Peripheral Bus Scaling mode is available where peripherals are clocked at the programmable fraction of the CPU clock (SYSCLK).

27.2 CPU Halted Methods

The device supports two power-saving modes, Sleep and Idle, both of which Halt the clock to the CPU. These modes operate with all clock sources, as listed below:

- POSC Idle mode: the system clock is derived from the POSC. The system clock source continues to operate. Peripherals continue to operate, but can optionally be individually disabled.
- FRC Idle mode: the system clock is derived from the FRC with or without postscalers. Peripherals continue to operate, but can optionally be individually disabled.
- SOSC Idle mode: the system clock is derived from the SOSC. Peripherals continue to operate, but can optionally be individually disabled.
- LPRC Idle mode: the system clock is derived from the LPRC. Peripherals continue to operate, but can optionally be individually disabled. This is the lowest power mode for the device with a clock running.
- Sleep mode: the CPU, the system clock source and any peripherals that operate from the system clock source are Halted. Some peripherals can operate in Sleep using specific clock sources. This is the lowest power mode for the device.

27.3 Power-Saving Operation

Peripherals and the CPU can be Halted or disabled to further reduce power consumption.

27.3.1 SLEEP MODE

Sleep mode has the lowest power consumption of the device power-saving operating modes. The CPU and most peripherals are Halted. Select peripherals can continue to operate in Sleep mode and can be used to wake the device from Sleep. See the individual peripheral module sections for descriptions of behavior in Sleep.

Sleep mode includes the following characteristics:

- The CPU is Halted.
- The system clock source is typically shutdown. See **Section 27.3.3 "Peripheral Bus Scaling Method"** for specific information.
- There can be a wake-up delay based on the oscillator selection.
- The Fail-Safe Clock Monitor (FSCM) does not operate during Sleep mode.
- The BOR circuit remains operative during Sleep mode.
- The WDT, if enabled, is not automatically cleared prior to entering Sleep mode.
- Some peripherals can continue to operate at limited functionality in Sleep mode. These peripherals include I/O pins that detect a change in the input signal, WDT, ADC, UART and peripherals that use an external clock input or the internal LPRC oscillator (e.g., RTCC, Timer1 and Input Capture).
- I/O pins continue to sink or source current in the same manner as they do when the device is not in Sleep.
- The USB module can override the disabling of the Posc or FRC. Refer to the USB section for specific details.
- Modules can be individually disabled by software prior to entering Sleep in order to further reduce consumption.

REGISTER 28-2: DEVCFG1: DEVICE CONFIGURATION WORD 1 (CONTINUED)

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits
- 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
- 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
- 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

bit 13-12 **FPBDIV<1:0>:** Peripheral Bus Clock Divisor Default Value bits
- 11 = PBCLK is SYSCLK divided by 8
- 10 = PBCLK is SYSCLK divided by 4
- 01 = PBCLK is SYSCLK divided by 2
- 00 = PBCLK is SYSCLK divided by 1

bit 11 **Reserved:** Write '1'

bit 10 **OSCIOFNC:** CLKO Enable Configuration bit
- 1 = CLKO output disabled
- 0 = CLKO output signal active on the OSCO pin; Primary Oscillator must be disabled or configured for the External Clock mode (EC) for the CLKO to be active (POSCMOD<1:0> = 11 or 00)

bit 9-8 **POSCMOD<1:0>:** Primary Oscillator Configuration bits
- 11 = Primary Oscillator disabled
- 10 = HS Oscillator mode selected
- 01 = XT Oscillator mode selected
- 00 = External Clock mode selected

bit 7 **IESO:** Internal External Switchover bit
- 1 = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
- 0 = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)

bit 6 **Reserved:** Write '1'

bit 5 **FSOSCEN:** Secondary Oscillator Enable bit
- 1 = Enable Secondary Oscillator
- 0 = Disable Secondary Oscillator

bit 4-3 **Reserved:** Write '1'

bit 2-0 **FNOSC<2:0>:** Oscillator Selection bits
- 111 = Fast RC Oscillator with divide-by-N (FRCDIV)
- 110 = FRCDIV16 Fast RC Oscillator with fixed divide-by-16 postscaler
- 101 = Low-Power RC Oscillator (LPRC)
- 100 = Secondary Oscillator (SOSC)
- 011 = Primary Oscillator (POSC) with PLL module (XT+PLL, HS+PLL, EC+PLL)
- 010 = Primary Oscillator (XT, HS, EC)**(1)**
- 001 = Fast RC Oscillator with divide-by-N with PLL module (FRCDIV+PLL)
- 000 = Fast RC Oscillator (FRC)

Note 1: Do not disable the POSC (POSCMOD = 11) when using this oscillator source.

TABLE 31-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage (Note 2)**	2.3	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/μs	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 31-10 for BOR values.

FIGURE 31-5: EXTERNAL RESET TIMING CHARACTERISTICS

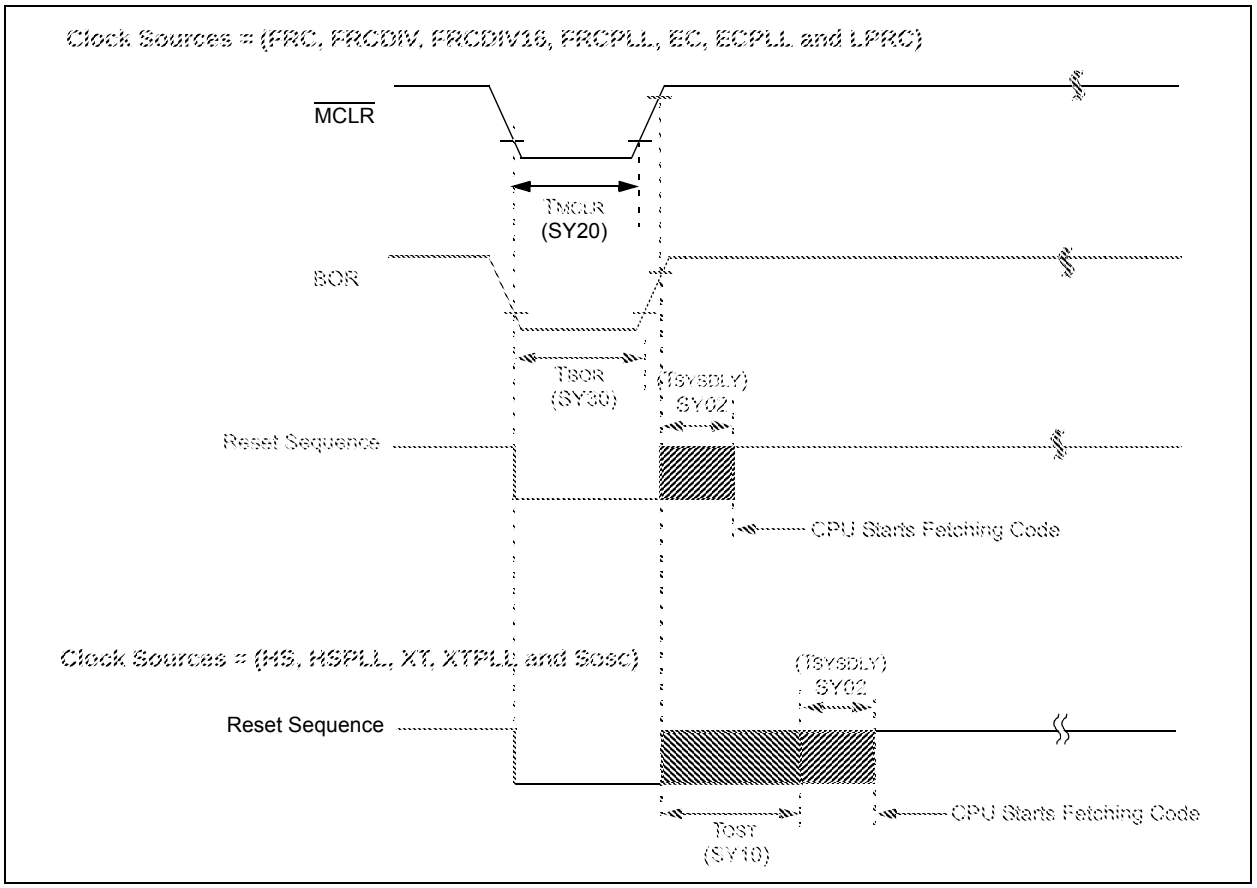


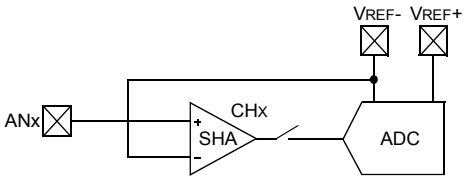
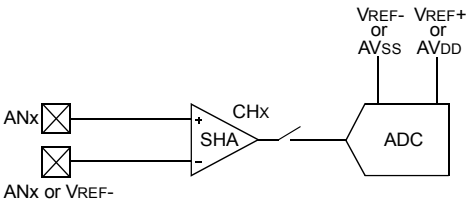
TABLE 31-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	μs	—
SY02	TSYSDLY	System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched.	—	1 μs + 8 SYSCLK cycles	—	—	—
SY20	TMCLR	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	—
SY30	TBOR	BOR Pulse Width (low)	—	1	—	μs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

TABLE 31-35: 10-BIT CONVERSION RATE PARAMETERS

AC CHARACTERISTICS(2)			Standard Operating Conditions (see Note 3): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
ADC Speed	**TAD Min.**	**Sampling Time Min.**	**RS Max.**	**VDD**	**ADC Channels Configuration**
1 Msps to 400 ksps(1)	65 ns	132 ns	500Ω	3.0V to 3.6V	
Up to 400 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	

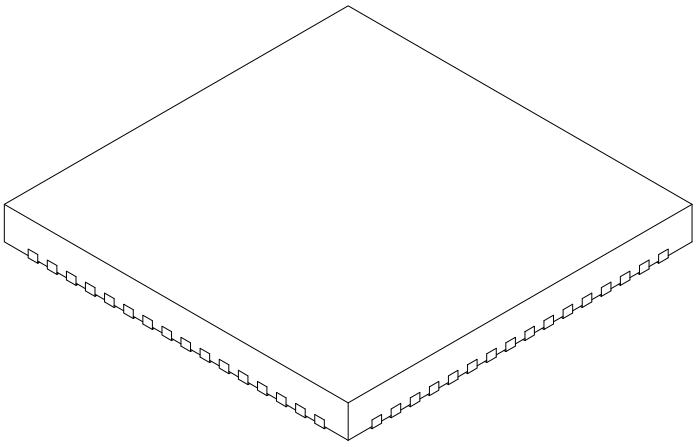
Note 1: External VREF- and VREF+ pins must be used for correct operation.

2: These parameters are characterized, but not tested in manufacturing.

3: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		64	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		9.00 BSC	
Exposed Pad Width	E2	5.30	5.40	5.50
Overall Length	D		9.00 BSC	
Exposed Pad Length	D2	5.30	5.40	5.50
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-154A Sheet 2 of 2

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
═ ISO/TS 16949 ═

Trademarks

ISBN: 978-1-5224-0488-0